

CORRECTION

[View Article Online](#)
[View Journal](#) | [View Issue](#)

Cite this: *J. Mater. Chem. C*, 2023, **11**, 15774

Correction: Copper particle-free ink with enhanced performance for inkjet-printed flexible UWB antennas

Wendong Yang, ^{ab} Zhichao Dong, ^{ab} Zihao Guo ^{ab} and Haoqiang Sun ^{ab}

DOI: 10.1039/d3tc90239k

rsc.li/materials-c

Correction for 'Copper particle-free ink with enhanced performance for inkjet-printed flexible UWB antennas' by Wendong Yang *et al.*, *J. Mater. Chem. C*, 2023, **11**, 14429–14438, <https://doi.org/10.1039/D3TC02515B>.

The authors regret an error in Fig. 4 of the published article, where Fig. 4a was unfortunately replaced with a duplicate of Fig. 4b. The corrected version of Fig. 4 is shown here (the caption remains unchanged).

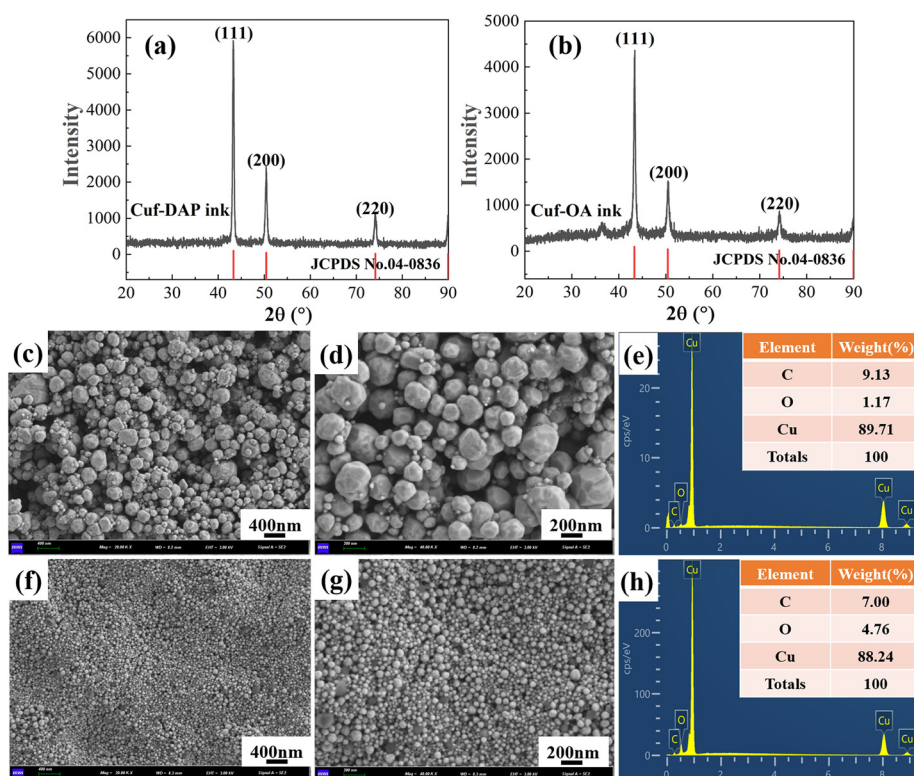


Fig. 4 XRD, surface morphologies and EDS results of the produced copper films from (a) and (c)–(e) Cuf-DAP ink and (b) and (f)–(h) Cuf-OA ink sintered at 170 °C for 60 minutes.

The Royal Society of Chemistry apologises for these errors and any consequent inconvenience to authors and readers.

^a School of Electronic and Information Engineering, Liaoning Technical University, No. 188, Longwan South Street, Huludao City, 125105 Liaoning, China.
E-mail: wendong_2007@163.com

^b Key Laboratory of Radio Frequency and Big Data for Intelligent Applications, Liaoning Technical University, Huludao City, 125105 Liaoning, China